

2201451

https://www.phoenixcontact.com/us/products/2201451

Please be informed that the data shown in this PDF document is generated from our online catalog. Please find the complete data in the user documentation. Our general terms of use for downloads are valid.



DIN rail housing for use in distribution boards in accordance with DIN 43880, modular upper housing part, width: 161.6 mm, height: 89.7 mm, depth: 54.85 mm, color: light grey (similar RAL 7035)

Your advantages

- · Coordinated housing and connection system for faster device development
- · Individual online configuration for diverse applications in building automation
- · Variety of connection technology
- Can be mounted on the DIN rail or the wall
- · With DIN-rail-mountable bus connector and power connector system as an option
- · Tool-free mounting
- Available in overall widths from one to nine HP (17.8 mm ... 161.6 mm)
- Compliant with DIN□EN□43880

Commercial data

Item number	2201451
Packing unit	10 pc
Minimum order quantity	10 pc
Note	Made to order (non-returnable)
Sales key	AC10
Product key	ACHBAB
Catalog page	Page 701 (C-1-2013)
GTIN	4046356806220
Weight per piece (including packing)	64.08 g
Weight per piece (excluding packing)	52.57 g
Customs tariff number	84879090
Country of origin	DE



Refer to the data sheet for the range in the download area.

2201451

https://www.phoenixcontact.com/us/products/2201451

Technical data

General

Notes

Product properties			
	Product type	Upper housing part	
	Housing series	BC	
	Product family	BC 161,6	
	Туре	modular upper housing part	
	Housing type	DIN rail housing for use in distribution boards in accordance with DIN 43880	

yes

Dimensions

Ventilation openings present

	d
Width	161.6 mm
Height	89.7 mm
Depth	54.85 mm
Horizontal pitch	9 Div.
CB design	
PCB thickness	1.4 mm 1.8 mm

Environmental and real-life conditions

Flammability rating according to UL 94

Vibration test

Color (Housing)

Housing material

Specification	IEC 60068-2-6:2007-12
Frequency	10 - 150 - 10 Hz
Sweep speed	1 octave/min
Amplitude	0.15 mm (10 Hz 58.1 Hz)
Acceleration	2g (58.1 Hz 150 Hz)
Test duration per axis	2.5 h

light grey (RAL 7035)

Polycarbonate



2201451

https://www.phoenixcontact.com/us/products/2201451

Specification IEC 60695-2-11:2014-02 Temperature 850 °C Time of exposure 30 s schanical strength / tumbling barrel IEC 60068-2-31:2008-05 Specification IEC 60068-2-31:2008-05 Height of fall 50 cm Frequency 50 ocks Specification Pulse shape Half-sine Acceleration 15g Shock duration 11 ms Number of shocks per direction 3 Test directions X-, Y- and Z-axis (pos. and neg.) gree of protection (IP code) Specification Specification IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-0 subject conditions Ambient conditions Max. IP code to attain IP20 Ambient temperature (operation) 40 °C 105 °C (depending on power dissipation) Ambient temperature (storage/transport) 40 °C 70 °C Ambient temperature (assembly) 5 °C 100 °C Relative humidity (storage/transport) 40 °C 70 °C Ambient temperature (assembly) 5 °C 100 °C Relative humidity (storage/t		
Temperature 850 °C Time of exposure 30 s techanical strength / tumbling barrel Specification IEC 60068-2-31:2008-05 Height of fall 50 cm Frequency 50 thocks Specification IEC 60068-2-27:2008-02 Half-sine Acceleration I5g Shock duration 11m Number of shocks per direction 3 Test directions X-, Y- and Z-axis (pos. and neg.) Specification IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-0 IMABER OF COMMENT OF COM	Glow-wire test	
Mechanical strength / tumbling barrel	Specification	IEC 60695-2-11:2014-02
	Temperature	850 °C
Specification IEC 60068-2-31:2008-05 Height of fall 50 cm	Time of exposure	30 s
Height of fall 50 cm	Mechanical strength / tumbling barrel	
Frequency 50 Shocks Specification IEC 60068-2-27:2008-02 Pulse shape Half-sine Acceleration 15g Shock duration 11 ms Number of shocks per direction 3 Test directions X-, Y- and Z-axis (pos. and neg.) Pegree of protection (IP code) Specification IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-0 Ambient conditions Max. IP code to attain IP20 Ambient temperature (operation) -40 °C 105 °C (depending on power dissipation) Ambient temperature (storage/transport) -40 °C 100 °C Relative humidity (storage/transport) 95 % B data Number of PCB holders 18 Type of PCB mount Latching Thickness of the PCB 1.4 mm 1.8 mm untting Mounting type Snap in Mounting position Vertical (horizontal DIN rail) ckaging specifications Type of packaging packed in cardboard	Specification	IEC 60068-2-31:2008-05
Specification IEC 60068-2-27:2008-02 Pulse shape Half-sine Acceleration 15g Shock duration 11 ms Number of shocks per direction 3 Test directions X-V. Y- and Z-axis (pos. and neg.) Degree of protection (IP code) Specification IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-0 Sumblent conditions Max. IP code to attain IP20 Ambient temperature (operation) -40 °C 105 °C (depending on power dissipation) Ambient temperature (storage/transport) -40 °C 70 °C Ambient temperature (assembly) -5 °C 100 °C Relative humidity (storage/transport) 95 % B data Number of PCB holders 18 Type of PCB mount Latching Thickness of the PCB 1.4 mm 1.8 mm unting Mounting type Snap in Mounting position Vertical (horizontal DIN rail) ckaging specifications Type of packaging packed in cardboard	Height of fall	50 cm
Specification IEC 60068-2-27:2008-02 Pulse shape Half-sine Acceleration 15g Shock duration 11 ms Number of shocks per direction 3 Test directions X-, Y- and Z-axis (pos. and neg.) Degree of protection (IP code) Specification IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-0 Subject to attain IP20 Ambient conditions Max. IP code to attain IP20 Ambient temperature (operation) -40 °C 105 °C (depending on power dissipation) Ambient temperature (storage/transport) -5 °C 100 °C Relative humidity (storage/transport) 95 % B data Number of PCB holders 18 Type of PCB mount Latching Thickness of the PCB 1.4 mm 1.8 mm unting Mounting type Snap in Mounting position Vertical (horizontal DIN rail) ckagging specifications Type of packaging packed in cardboard	Frequency	50
Pulse shape Acceleration 15g Shock duration 11 ms Number of shocks per direction 3 Test directions X-, Y- and Z-axis (pos. and neg.) Degree of protection (IP code) Specification IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-0 Windows and the short of the short	hocks	
Acceleration 15g Shock duration 11 ms Number of shocks per direction 3 Test directions X-, Y- and Z-axis (pos. and neg.) Degree of protection (IP code) Specification IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-0 Ambient conditions Max. IP code to attain IP20 Ambient temperature (operation) -40 °C 105 °C (depending on power dissipation) Ambient temperature (storage/transport) -5 °C 100 °C Relative humidity (storage/transport) 95 % B data Number of PCB holders 18 Type of PCB mount Latching Thickness of the PCB 1.4 mm 1.8 mm unting Mounting type Snap in Mounting position Vertical (horizontal DIN rail) ckaging specifications Type of packaging packed in cardboard	Specification	IEC 60068-2-27:2008-02
Shock duration 11 ms Number of shocks per direction 3 Test directions X-, Y- and Z-axis (pos. and neg.) Degree of protection (IP code) Specification IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-0 IEC 60529:1989-11 + AMD 1:1999-11	Pulse shape	Half-sine
Number of shocks per direction Test directions X-, Y- and Z-axis (pos. and neg.) Degree of protection (IP code) Specification IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-0 IEC 60529:1989-11 + AMD 2:2013-0 IEC 60529:1989-11 + AMD 1:1999-	Acceleration	15g
Test directions X-, Y- and Z-axis (pos. and neg.) Degree of protection (IP code) Specification IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-0 Ambient conditions Max. IP code to attain IP20 Ambient temperature (operation) -40 °C 105 °C (depending on power dissipation) Ambient temperature (storage/transport) -5 °C 100 °C Ambient temperature (assembly) -5 °C 100 °C Relative humidity (storage/transport) 95 % B data Number of PCB holders 18 Type of PCB mount Latching Thickness of the PCB 1.4 mm 1.8 mm unting Mounting type Snap in Mounting type Snap in Mounting specifications Type of packaging packed in cardboard	Shock duration	11 ms
Degree of protection (IP code) Specification IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-0 Ambient conditions Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly) -5 °C 100 °C Relative humidity (storage/transport) 95 % B data Number of PCB holders 18 Type of PCB mount Latching Thickness of the PCB 1.4 mm 1.8 mm unting Mounting type Snap in Mounting position Vertical (horizontal DIN rail) ckaging specifications Type of packaging packed in cardboard	Number of shocks per direction	3
Specification IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-0 Ambient conditions Max. IP code to attain IP20 Ambient temperature (operation) -40 °C 105 °C (depending on power dissipation) Ambient temperature (storage/transport) -40 °C 70 °C Ambient temperature (assembly) -5 °C 100 °C Relative humidity (storage/transport) 95 % B data Number of PCB holders 18 Type of PCB mount Latching Thickness of the PCB 1.4 mm 1.8 mm unting Mounting type Snap in Mounting position Vertical (horizontal DIN rail) ckaging specifications Type of packaging packed in cardboard	Test directions	X-, Y- and Z-axis (pos. and neg.)
Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (storage/transport) Ambient temperature (assembly) -5 °C 70 °C -5 °C 100 °C Relative humidity (storage/transport) 95 % B data Number of PCB holders Type of PCB mount Thickness of the PCB 1.4 mm 1.8 mm unting Mounting type Snap in Mounting position Vertical (horizontal DIN rail) ckaging specifications Type of packaging packed in cardboard	Specification	IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-08
Ambient temperature (operation) Ambient temperature (storage/transport) -40 °C 70 °C Ambient temperature (assembly) -5 °C 100 °C Relative humidity (storage/transport) 95 % B data Number of PCB holders Type of PCB mount Thickness of the PCB Mounting Mounting type Snap in Mounting position Vertical (horizontal DIN rail) ckaging specifications Type of packaging packed in cardboard		IEC 60529:1989-11 + АМD 1:1999-11 + АМD 2:2013-08
Ambient temperature (storage/transport) Ambient temperature (assembly) -5 ° C 100 ° C Relative humidity (storage/transport) B data Number of PCB holders Type of PCB mount Thickness of the PCB Mounting Mounting type Snap in Mounting position Vertical (horizontal DIN rail) ckaging specifications Type of packaging packed in cardboard	mbient conditions	
Relative humidity (storage/transport) B data Number of PCB holders Type of PCB mount Thickness of the PCB 1.4 mm 1.8 mm unting Mounting type Snap in Mounting position Vertical (horizontal DIN rail) ckaging specifications Type of packaging packed in cardboard	mbient conditions Max. IP code to attain	IP20
Number of PCB holders 18 Type of PCB mount Latching Thickness of the PCB 1.4 mm 1.8 mm unting Mounting type Snap in Mounting position Vertical (horizontal DIN rail) ckaging specifications Type of packaging packed in cardboard	mbient conditions Max. IP code to attain Ambient temperature (operation)	IP20 -40 °C 105 °C (depending on power dissipation)
Number of PCB holders Type of PCB mount Latching Thickness of the PCB 1.4 mm 1.8 mm unting Mounting type Snap in Mounting position Vertical (horizontal DIN rail) ckaging specifications Type of packaging packed in cardboard	Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport)	IP20 -40 °C 105 °C (depending on power dissipation) -40 °C 70 °C
Type of PCB mount Thickness of the PCB 1.4 mm 1.8 mm unting Mounting type Snap in Mounting position Vertical (horizontal DIN rail) ckaging specifications Type of packaging packed in cardboard	Ambient conditions Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly)	IP20 -40 °C 105 °C (depending on power dissipation) -40 °C 70 °C -5 °C 100 °C
Thickness of the PCB 1.4 mm 1.8 mm unting Mounting type Snap in Vertical (horizontal DIN rail) ckaging specifications Type of packaging packed in cardboard	Ambient conditions Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly) Relative humidity (storage/transport)	IP20 -40 °C 105 °C (depending on power dissipation) -40 °C 70 °C -5 °C 100 °C
Mounting type Mounting position Mounting position Vertical (horizontal DIN rail) ckaging specifications Type of packaging packed in cardboard	Ambient conditions Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly) Relative humidity (storage/transport)	IP20 -40 °C 105 °C (depending on power dissipation) -40 °C 70 °C -5 °C 100 °C 95 %
Mounting type Snap in Mounting position Vertical (horizontal DIN rail) ckaging specifications Type of packaging packed in cardboard	Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly) Relative humidity (storage/transport) B data Number of PCB holders	IP20 -40 °C 105 °C (depending on power dissipation) -40 °C 70 °C -5 °C 100 °C 95 %
Mounting type Snap in Mounting position Vertical (horizontal DIN rail) ckaging specifications Type of packaging packed in cardboard	Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly) Relative humidity (storage/transport) B data Number of PCB holders Type of PCB mount	IP20 -40 °C 105 °C (depending on power dissipation) -40 °C 70 °C -5 °C 100 °C 95 % 18 Latching
Mounting position Vertical (horizontal DIN rail) ckaging specifications Type of packaging packed in cardboard	Ambient conditions Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly) Relative humidity (storage/transport) B data Number of PCB holders Type of PCB mount Thickness of the PCB	IP20 -40 °C 105 °C (depending on power dissipation) -40 °C 70 °C -5 °C 100 °C 95 % 18 Latching
Type of packaging packed in cardboard	Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly) Relative humidity (storage/transport) B data Number of PCB holders Type of PCB mount Thickness of the PCB	IP20 -40 °C 105 °C (depending on power dissipation) -40 °C 70 °C -5 °C 100 °C 95 % 18 Latching 1.4 mm 1.8 mm
Type of packaging packed in cardboard	Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly) Relative humidity (storage/transport) B data Number of PCB holders Type of PCB mount Thickness of the PCB unting Mounting type	IP20 -40 °C 105 °C (depending on power dissipation) -40 °C 70 °C -5 °C 100 °C 95 % 18 Latching 1.4 mm 1.8 mm
	Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly) Relative humidity (storage/transport) B data Number of PCB holders Type of PCB mount Thickness of the PCB unting Mounting type Mounting position	IP20 -40 °C 105 °C (depending on power dissipation) -40 °C 70 °C -5 °C 100 °C 95 % 18 Latching 1.4 mm 1.8 mm
	Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly) Relative humidity (storage/transport) B data Number of PCB holders Type of PCB mount Thickness of the PCB unting Mounting type Mounting position ckaging specifications	IP20 -40 °C 105 °C (depending on power dissipation) -40 °C 70 °C -5 °C 100 °C 95 % 18 Latching 1.4 mm 1.8 mm Snap in Vertical (horizontal DIN rail)



2201451

https://www.phoenixcontact.com/us/products/2201451

Classifications

ECLASS

	ECLASS-11.0	27182702
	ECLASS-13.0	27190603
ETIM		
	ETIM 9.0	EC001031
	Johan	
UNSPSC		
	UNSPSC 21.0	31261500



2201451

https://www.phoenixcontact.com/us/products/2201451

Environmental product compliance

China RoHS	Environmentally friendly use period: unlimited = EFUP-e
	No hazardous substances above threshold values

Phoenix Contact 2024 © - all rights reserved https://www.phoenixcontact.com

Phoenix Contact USA 586 Fulling Mill Road Middletown, PA 17057, United States (+717) 944-1300 info@phoenixcon.com